



LABORATORY RESULTS

Material Testing

FLUX INDUCED CORROSION (COPPER MIRROR METHOD)

J-STD-004, '95 IPC-TM-650
TEST METHODS MANUAL 2.3.32.

Laboratory	:	Interflux [®] Electronics NV, Belgium
Flux in test	:	Interflux[®] Solderingflux IF 2005C
Test mirror Numbers	:	2
Control Mirror Number	:	n°1
Test Method Begins	:	15.02.2001
Test Method End	:	16.02.2001

Result

* There is no discoloration or removal of the copper film

Interflux[®] Solderingflux IF 2005C passes the copper mirror test

Our reports pertain to the sample tested only.
Information contained herein is not to be produced,
except with our permission.

Interflux[®] Electronics NV



LABORATORY RESULTS

Material Testing

PRESENCE OF HALIDES IN FLUX, SILVER CHROMATE METHOD

J-STD-004, '95 IPC-TM-650
TEST METHODS MANUAL 2.3.33.

Laboratory	:	Interflux [®] Electronics NV, Belgium
Flux in test	:	Interflux[®] Solderingflux IF 2005C
Test paper Numbers	:	6
Test Method Begins	:	15.02.2001
Test Method End	:	15.02.2001

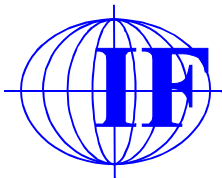
Result

* There is no colour change on the test papers.

Interflux[®] Solderingflux IF 2005C passes the Silver Chromate test.

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LABORATORY RESULTS

Material Testing

DETERMINATION OF ACID VALUE OF LIQUID SOLDER FLUX VISUAL TITRATION METHOD

Laboratory	:	Interflux® Electronics NV, Belgium
Flux in test	:	Interflux® Solderingflux IF 2005C
Test samples	:	2
Test Method Begins	:	15.02.2001
Test Method End	:	15.02.2001

Result

* The acid value is expressed in milligrams of Potassium Hydroxide per gram of non-volatile matter.

**The average acid value of Interflux® SolderingfluxIF 2005C
= 29 mg KOH/g**

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LABORATORY RESULTS

Material Testing

SURFACE INSULATION RESISTANCE TEST
J-STD-004, '95 IPC-TM-650
TEST METHODS MANUAL 2.6.3.3.

Laboratory : Interflux® Electronics NV, Belgium
Flux in test : **Interflux® Solderingflux IF 2005C**
Test Board Numbers : 3
Control Board Number : 1
Chamber Operation Begins : 15.02.2001
Chamber operation : 85°C and 85% R.H

<u>Measurement</u>	<u>Date/Time</u>	<u>Required Ohms (min.)</u>	<u>Results</u>
Ti (initial resistance)	15/02 : 12u00	-----	-----
T0 (bias voltage applied)	15/02 : 16u15	-----	-----
T1 (24 hours exposure)	16/02 : 16u15	1 x 10 ⁸	Passed
T2 (96 hours exposure)	19/02 : 16u15	1 x 10 ⁸	Passed
T3 (168 hours exposure)	22/02 : 16u15	1 x 10 ⁸	Passed

Evaluation - Remark

Board 1 : Pattern Control

Board 2 : Pattern solderside up/not cleaned

Board 3 : Pattern solderside down/not cleaned

Board 4: Pattern solderside down/not cleaned

Remark: Before entering the test chamber

Board 4: Pattern B: removal of 2 short-circuits

(Alloy - solderbath: Sn99.3Cu0.7)

After 168 Hours into the humidity chamber we have done a visual control on board 1, board 2, board 3 and board 4. There was **no** dendrith growth present.

Conclusion

Interflux® Solderingflux IF 2005C passes the SIR test.

(please refer to graphic enclosed)

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LABORATORY RESULTS

Material Testing

SURFACE INSULATION RESISTANCE TEST
J-STD-004, '95 IPC-TM-650
TEST METHODS MANUAL 2.6.3.3.

INTERFLUX[®] SOLDERING FLUX IF 205C

